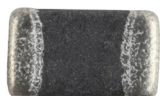


MCL2012V1

Multilayer chip inductor



Product features

- 0805 (2012 metric) package
- Low DC resistance, high current
- Multilayer monolithic construction yields high reliability
- Suitable for wave and reflow soldering
- Inductance range from 0.047 μ H to 22 μ H
- Moisture sensitivity level (MSL): 1

Applications

- Industrial connectivity (IoT)
- Wireless communications
 - Bluetooth
 - WiFi
 - Antenna
- Machine-to-machine (M2M)
- Mobile phones
- Wearable devices
- Wireless LAN
- Computing/gaming consoles
- Broadband components
- RF transceiver modules

Environmental data

- Operating temperature range: -40 °C to +85 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 (latest revision) compliant



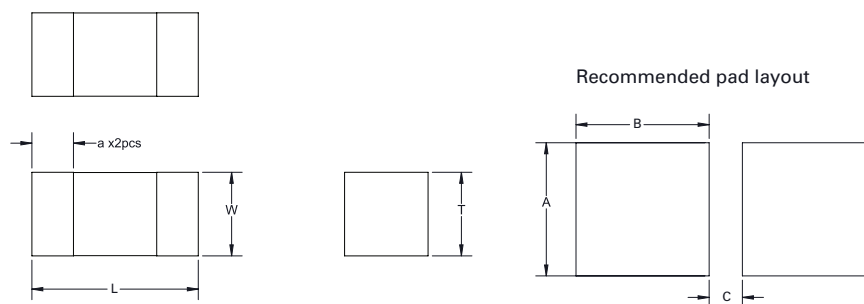
Product specifications

Part number	OCL (uH) ±20%	I Rated (mA) maximum	DCR (Ω) maximum @ +25°C	SRF (MHz) minimum	Test frequency (MHz)	Test voltage (mV)
MCL2012V1-R047-R	0.047	350	0.15	320	1.0	50
MCL2012V1-R056-R	0.056	350	0.15	320	1.0	50
MCL2012V1-R068-R	0.068	350	0.20	280	1.0	50
MCL2012V1-R082-R	0.082	350	0.20	280	1.0	50
MCL2012V1-R100-R	0.10	350	0.20	235	1.0	50
MCL2012V1-R120-R	0.120	350	0.20	220	1.0	50
MCL2012V1-R150-R	0.150	350	0.20	200	1.0	50
MCL2012V1-R180-R	0.180	300	0.25	185	1.0	50
MCL2012V1-R220-R	0.220	300	0.25	170	1.0	50
MCL2012V1-R270-R	0.270	300	0.25	150	1.0	50
MCL2012V1-R330-R	0.330	300	0.25	145	1.0	50
MCL2012V1-R390-R	0.390	250	0.30	135	1.0	50
MCL2012V1-R470-R	0.470	250	0.30	125	1.0	50
MCL2012V1-R560-R	0.560	200	0.36	115	1.0	50
MCL2012V1-R680-R	0.680	200	0.36	105	1.0	50
MCL2012V1-R820-R	0.820	200	0.36	100	1.0	50
MCL2012V1-1R0-R	1.0	220	0.26	75	1.0	50
MCL2012V1-1R2-R	1.2	220	0.26	65	1.0	50
MCL2012V1-1R5-R	1.5	180	0.30	60	1.0	50
MCL2012V1-1R8-R	1.8	180	0.30	55	1.0	50
MCL2012V1-2R2-R	2.2	150	0.36	50	1.0	50
MCL2012V1-2R7-R	2.7	150	0.36	45	1.0	50
MCL2012V1-3R3-R	3.3	120	0.40	41	1.0	50
MCL2012V1-3R9-R	3.9	120	0.40	38	1.0	50
MCL2012V1-4R7-R	4.7	120	0.40	35	1.0	50
MCL2012V1-5R6-R	5.6	100	0.60	32	1.0	50
MCL2012V1-6R8-R	6.8	100	0.60	29	1.0	50
MCL2012V1-8R2-R	8.2	100	0.65	26	1.0	50
MCL2012V1-100-R	10	100	0.65	24	1.0	50
MCL2012V1-120-R	12	100	0.65	22	1.0	50
MCL2012V1-150-R	15	50	0.75	19	1.0	50
MCL2012V1-180-R	18	50	0.75	18	1.0	50
MCL2012V1-220-R	22	50	0.75	16	1.0	50

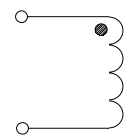
1. Test frequency and voltage at +25 °C
2. Resistance to soldering heat: +260 ±5 °C for 10 ± 1 second
3. At low temperature (-40 ±2°C) the inductance change is within ±10%
4. At high temperature (+85 ±2°C) the inductance change is within ±10%
5. Rated I: When rated I is applied to the product, self-temperature rise will be 40 °C or less.

6. Part Number Definition: MCL2012V1-xxx-R
MCL2012 = Product code and size
V1= Version indicator
xxx= inductance value in uH, R= decimal point,
If no R is present then last character equals number of zeros
-R suffix = RoHS compliant

Dimensions (mm)



Schematic



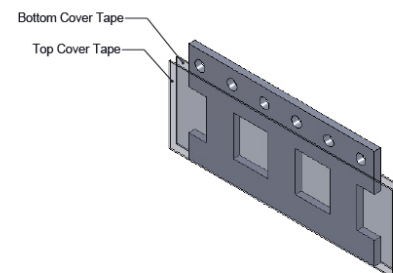
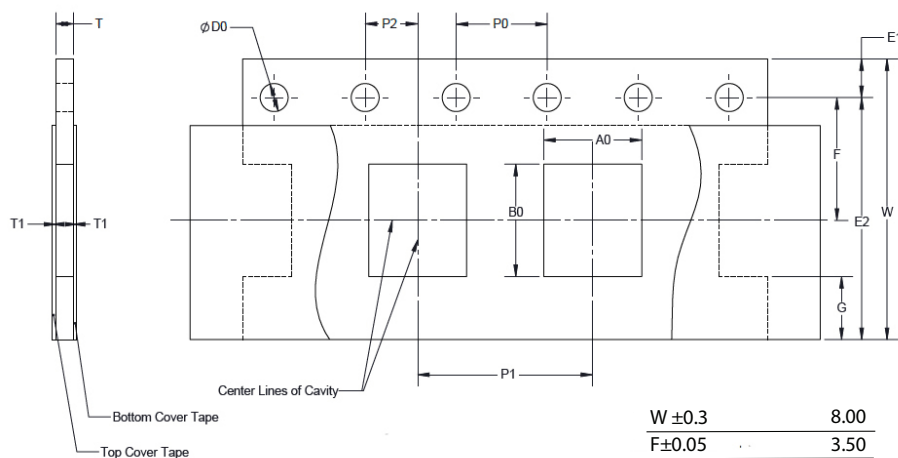
Part Number	L	W	T	a	A	B	C
MCL2012V1-xxx-R	2.0 ±0.20	1.2 ±0.20	0.90 ±0.20	0.50 ±0.30	1.6 ±0.10	1.2 ±0.10	04 ±0.10

No part marking
All soldering surfaces to be coplanar within 0.1 millimeters
Tolerances are ±0.2 millimeters unless stated otherwise
Pad layout tolerances are ±0.1 millimeters unless stated otherwise
Do not route traces or vias underneath the inductor

Packaging information (mm)

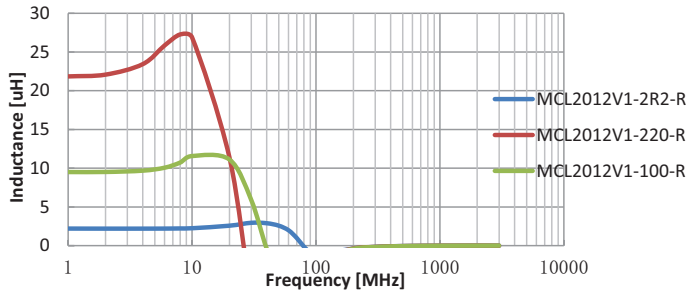
Drawing not to scale

Supplied in tape and reel packaging, 4000 parts per 7" diameter reel

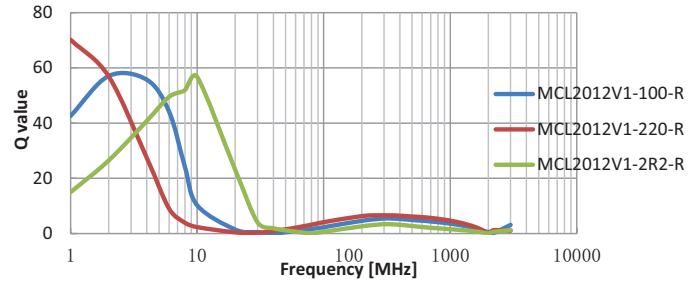


W ±0.3	8.00
F ±0.05	3.50
E1 ±0.10	1.75
E2 Min	6.25
P0 ±0.10	4.00
P1 ±0.2	4.00
P2 ±0.1	2.00
D0 ±0.10/-0	1.50
A0	1.5 ±0.20
B0	2.3 ±0.20
T Max	1.10
T1 Max	na

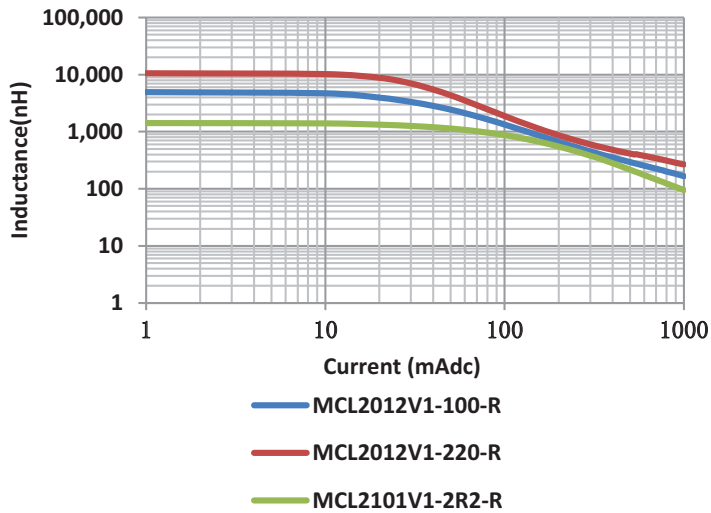
Inductance vs frequency



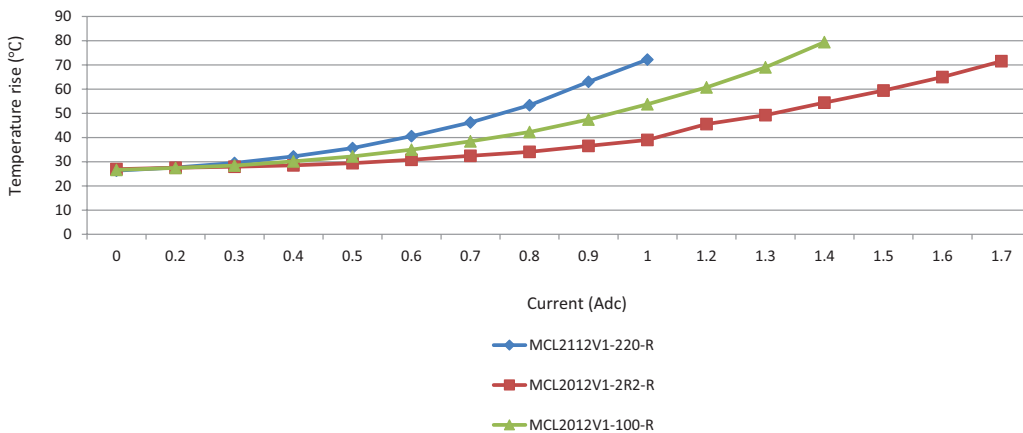
Q vs frequency



Inductance vs current



Temperature rise vs current



Solder reflow profile

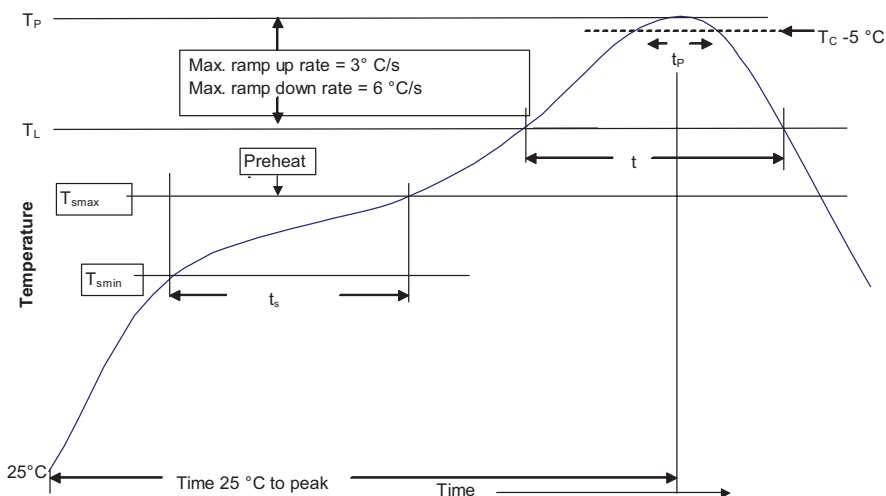


Table 1 - Standard SnPb solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm)	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2 - Lead (Pb) free solder (T_C)

Package thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

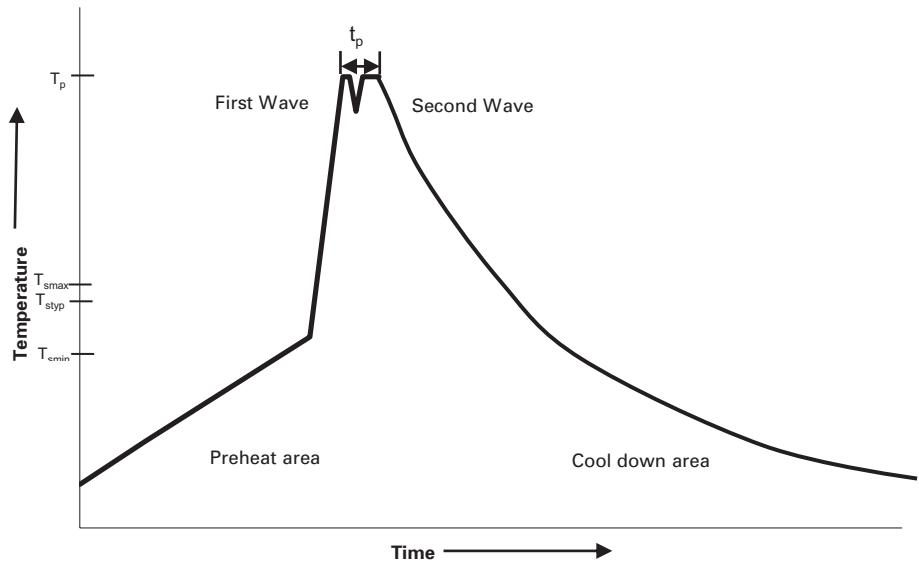
Reference J-STD-020

Profile feature	Standard SnPb solder	Lead (Pb) free solder
Preheat and soak		
• Temperature min. (T_{smin})	100 °C	150 °C
• Temperature max. (T_{smax})	150 °C	200 °C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds	60-120 seconds
Average ramp up rate T_{smax} to T_P	3 °C/ second max.	3 °C/ second max.
Liquidous temperature (T_L)	183 °C	217 °C
Time at liquidous (t_L)	60-150 seconds	60-150 seconds
Peak package body temperature (T_P)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_C)	10 seconds**	10 seconds**
Average ramp-down rate (T_P to T_{smax})	6 °C/ second max.	6 °C/ second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

Wave solder profile



Reference EN 61760-1:2006

Profile feature	Standard SnPb solder	Lead (Pb) free solder
Preheat		
• Temperature min. (T_{smin})	100 °C	100 °C
• Temperature typ. (T_{styp})	120 °C	120 °C
• Temperature max. (T_{smax})	130 °C	130 °C
• Time (T_{smin} to T_{smax}) (t_s)	70 seconds	70 seconds
Δ preheat to max Temperature	150 °C max.	150 °C max.
Peak temperature (T_p)*	235 °C – 260 °C	250 °C – 260 °C
Time at peak temperature (t_p)	10 seconds max 5 seconds max each wave	10 seconds max 5 seconds max each wave
Ramp-down rate	~ 2 K/s min ~3.5 K/s typ ~5 K/s max	~ 2 K/s min ~3.5 K/s typ ~5 K/s max
Time 25 °C to 25 °C	4 minutes	4 minutes

Manual solder

+350 °C, 4-5 seconds. (by soldering iron), generally manual, hand soldering is not recommended.

Life Support Policy: Eaton does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Company. Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

Eaton reserves the right, without notice, to change design or construction of any products and to discontinue or limit distribution of any products. Eaton also reserves the right to change or update, without notice, any technical information contained in this bulletin.

Eaton
Electronics Division
1000 Eaton Boulevard
Cleveland, OH 44122
United States
www.eaton.com/electronics

© 2019 Eaton
All Rights Reserved
Printed in USA
Publication No. 10928 BU-MC19060
June 2019

Eaton is a registered trademark.

All other trademarks are property
of their respective owners.

Follow us on social media to get the
latest product and support information.





Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.